



Here is the agenda. Today, we have a guest speaker, Mr. Lee, from Applied Materials, a shareholder and collaboration partner of our company. In part one, Mr. Lee will share his view of the industry as a whole, and then I will give an overview of KOKUSAI ELECTRIC. After that, with Mr. Lee, we will have a Q&A session about the industry and KOKUSAI as a whole followed by a break.

After short break, part two will be a detailed explanation of KOKUSAI's strategy for each device, followed by Q&A session with the presenters who are executive officers. The session will be three hours long, but we will make every effort to deepen the part







We had just had our earnings call, so I urge you to look at the earnings call online. It was announced on May 16. The details on outlook and specific projections can be found there and in its transcripts. In the







Again, I talk about these end market inflections or these megatrends around AI, ~~life~~, renab

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This is specifically discussing the use of the term "omplussy seus51s" in the context of the document.





You can see the same challenges that our customers are facing. If you look at the ability to stack multiple DRAM die, it will require high aspect ratio etch. It will require TSV and advanced packaging. You can also see the same challenges that our customers are facing. It will require high aspect ratio etch. It will require TSV and advanced packaging. You can also see the same challenges that our customers are facing. It will require high aspect ratio etch. It will require TSV and advanced packaging.







I want to talk about the third theme that I have is innovating how45(hgys ihowl rd tIP()6C



In closing, long-

Next, I Kanai, will give you an overview of our company.













The drivers for materializing growth exceeding WFE markets exist in each respective area. In addition to the common trend of devices becoming more three-

